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Approved by:	Reviewed by:	Produced by:

## **CJTCONN** 長江連接器有限公司 CHANGJIANG CONNECTORS CO.,LTD.

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## 1. Scope:

This product specification contains the test results that general performances of A1256 SERIES connector were examined.

## 2. Part name & part number:

Part name	Part number		
Housing	A1256H		
Terminal	A1256-T		
Wafer	A1256WR-S,A1256WRA-S		

## 3. Construction \( \) dimensions \( \) material & surface finish :

Construction and dimensions shall be in accordance with the referenced drawings.

Material and surface finish shall be as specified below.

Part 1	name	Material	Surface finish
Housing		Nylon 66	UL 94V-0
Teri	minal	Phosphor Bronze	Gold-plated
	Post	Brass	Tin-plated
Wafer	Body	Nylon6T/LCP	UL 94V-0
(SMT)	Tab	Brass	Tin-plated

## 4. Characteristics:

Current rating: 1A AC,DC

Voltage rating: 200V AC,DC

Temperature range :  $-40^{\circ}$ C  $\sim 105^{\circ}$ C

#### 5. Conditions:

The conditions shall be in accordance with the referenced drawing of next page.

Number	Item	Requirement
	Bend up	4° max.
	Bend down	4° max.
(1)	Twisting	3° max.
	Rolling	8° max.
(2)	Bell mouth (flare)	0.2-0.5 mm
(3)	Cut-off tab length	0.2 mm max.
(4)	Extruded wire length	0-0.5 mm
(5)	Seam	Seam shall not be opened and no wire allowed out of crimping area
	Wire strip length	1.2-1.7 mm ref.
(8)	Lance height	0.3 mm ref.

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## 6. Mechanical test:

6.1 Crimp width \ crimp height & crimp strength

After crimping, the crimped areas [(6), (7)] should be as follows.

Wire	Terminal	Conductor(mm)		Insulation(mm)		Crimp
Size	Part	Crimp	Crimp Crimp Crimp		Crimp	Strength
(AWG)	Number	Width	Height	Width	Height	(Kg)
#28			0.59~0.68		0.80(max)	1.0(min)
#30	A1256-T	$0.8\pm0.15$	0.55~0.64	0.95	0.70(max)	0.5(min)
#32			0.51~0.60	(max)	0.60(max)	0.4(min)

Note: no distorted after terminal crimped.

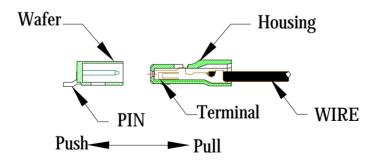
6.2 Insertion force (I.F.) & withdrawal force (W.F.)

(1) Requirement: (Single Row)

Number of	At	initial	At 50th
Circuits	I.F. (max)	W.F. (min)	W.F. (min)
Single	0.80Kg	0.05Kg	0.04Kg
2P	1.00Kg	0.08Kg	0.06Kg
20P	6.00Kg	0.80Kg	0.70Kg
30P	8.00Kg	1.20Kg	1.10Kg

(2) Test method: Housing with crimped terminal and wafer shall be mated and unmated on the same axis. Initial insertion and withdrawal forces and withdrawal forces at 30th shall be measured for single circuit and multi-circuits. For the measurement of single circuit, housing lock shall be removed.

Insertion and withdrawal speed: 20±5 mm/minute.



(3) Test results: (Single Row)

Number of		At initial		At initial		AT 50th
Circuits	ircuits		W.F. (Kg)	W.F. (Kg)		
	Max.	0.42	0.28	0.24		
Single	Min.	0.29	0.20	0.16		
	Ave.	0.33	0.23	0.20		

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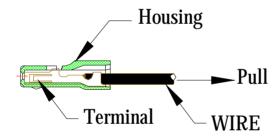
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2P	Max.	0.69	0.42	0.36
	Min.	0.46	0.34	0.27
	Ave.	0.58	0.38	0.31
20P	Max.	3.38	1.62	1.51
	Min.	1.89	1.19	1.02
	Ave.	2.86	1.50	1.42
	Max.	4.25	2.86	2.68
30P	Min.	2.52	2.02	1.89
	Ave.	3.58	2.62	2.51

## 6.2 Post retention force

(1) Requirement: 0.5 Kg (min.)

(2) Test method: Crimped terminal shall be mounted in a housing and pulled in an alignment. The load to pull the terminal out of the housing shall be measured.



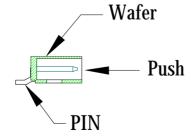
#### (3) Test results:

Max.	Min.	Ave.	N=10
1.62Kg	1.02 Kg	1.27 Kg	

## 6.4 Post retention force

(1) Requirement : 0.5Kg (min.)

(2) Test method: The end of a post shall be pushed in a perpendicular to wafer. The load to make the post start moving shall be measured.



#### (3) Test results:

Max.	Min.	Ave.	N=10
1.49 Kg	1.01 Kg	1.27 Kg	



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#### 7. Electrical test:

#### 7.1 Contact resistance

(1) Requirement : Initial :  $40 \text{ m}\Omega$  (max.)

After environmental test :  $50 \text{ m}\Omega$  (max.)

(2) Condition: Test current: 10 mA (DC)

Open voltage: 20mV (max.)

(3) Test result : See items  $8.1 \sim 8.4$ 

#### 7.2 Insulation resistance

(1) Requirement : Initial :  $100 \text{ M}\Omega$  (min.)

After humidity test : 50 M $\Omega$  (min.)

After thermal shock test : 50 M $\Omega$  (min.)

(2) Test method: DC 500V shall be applied between outer surface of housing and terminal and between adjacent terminals to measure insulation resistance.

(MIL-STD-202, test method 302, condition B)

(3) Test result: See items 8.1 & 8.3

## 7.3 Dielectric withstanding voltage

- (1) Requirement: There shall be no breakdown nor flashover.
- (2) Test method: Initially AC 500V (rms) and after humidity and thermal shock tests AC 250V (rms) shall be applied between outer surface of housing and terminal and between adjacent terminals for one minutes. (MIL-STD-202, test method 301)

Test current: 1mA

(3) Test result: See items 8.1 & 8.3

#### 8. Environment test:

## 8.1 Humidity

- (1) Requirement: Contact resistance shall be 50 milliohms (max.) after the test. Insulation resistance shall be 250 megohms (min.) after the test. There shall be no breakdown nor flashover on dielectric withstanding voltage test.
- (2) Test method: Mated connector shall be placed in a humidity chamber of the following conditions. After the test, contact resistance, insulation resistance and dielectric withstanding voltage shall be measured. (MIL-STD-202, test method 103, condition A)

Temperature : 40±2 °C

Humidity: 90% ~ 95% (RH)

Period: 240 hours continuously

## (3) Test results:

Test item	Initial $(m\Omega)$			Aft	ter test (ms	2)
Contact	Max.	Min.	Ave.	Max.	Min	Ave
resistance	8.7	5.6	6.9	9.8	6.8	7.9

N=30

N = 20

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Test item	Housing-Terr	minal $(M\Omega)$	Terminal	-Terminal (M $\Omega$ )
Insulation	Initial After test		Initial	After test
resistance	500 min.	250 min.	500 min.	250 min.



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Test item	Housing-Terminal (M $\Omega$ )		Terminal-Te		
D.W.V.	Initial After test		Initial	After test	
	Good	Good	Good	Good	N=20

(D.W.V.: Dielectric withstanding voltage)

## 8.2 Salt spray

(1) Requirement: Contact resistance shall be 50 milliohms (max.) after the test.

(2) Test method: Mated connector shall be subjected to salt spray test of the following conditions. After the test, specimen shall be washed with running water and dried naturally before the measurement of contact resistance.

> Temperature: 40±2° Salt Solution Concentration: 5%

Humidity: 90% ~ 95% (RH)

Period: 8 or 16 or 24 or 32 or 48 hours

(3) Test result:

Test item	Initial (m $\Omega$ )			Af	ter test (ms	2)
Contact	Max.	Min.	Ave.	Max.	Min.	Ave.
resistance	8.8	5.7	7.3	9.2	6.3	7.8

N = 30

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#### 8.3 Thermal shock

- (1) Requirement: Contact resistance shall be 50 milliohms (max.) after the test. Insulation resistance shall be 250 megohms (min.) after the test. There shall be no breakdown nor flashover on dielectric withstanding voltage test.
- (2) Test method: Mated connector shall be subjected to thermal shock test of the following conditions. After the test, contact resistance, insulation resistance and dielectric withstanding voltage shall be measured.

1 cycle consists of:

-55 °C for 30 minutes

+85 °C for 30 minutes

Times of cycles: 25 cycles

#### (3) Test results:

Test item	Initial (m $\Omega$ )			After test $(m\Omega)$		
Contact	Max. Min. Ave.			Max.	Min.	Ave.
resistance	8.9	5.8	7.1	9.7	6.4	8.3

N = 20

N = 20

Test item	Housing-Terminal (M $\Omega$ )		Terminal-Terminal (M	
Insulation	Initial After test		Initial	After test
resistance	500 min.	250 min.	500 min.	250 min.

Test item	Housing-Ter	minal $(M\Omega)$	Terminal-Ter	rminal (M $\Omega$ )
D.W.V.	Initial After test		Initial	After test
	Good	Good	Good	Good

D.W.V.: Dielectric withstanding voltage

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(2) Test method: Mated connector shall be mounted on a PCB and subjected to a vibration test of the following conditions. During the test, current continuity shall

be checked. After the test, contact resistance shall be measured.

(MIL-STD-202, test method 201)

Frequency: 10~55~10 Hz/min.

Amplitude: 1.5 mm

Direction: 1. Axis of up and down

2. Axis of right and left

3. Axis of front and back

(3) Test result:

Test item	Initial $(m\Omega)$			Af	ter test (ms	2)
Contact	Max. Min. Ave.			Max.	Min	Ave.
resistance	8.7	6.8	7.5	9.3	6.9	7.8

N = 30

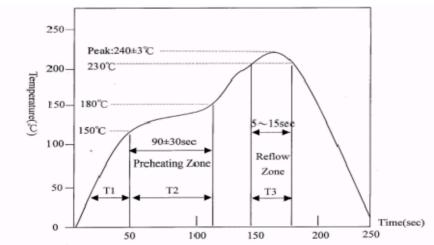
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Current discontinuity: There shall be no current discontinuity longer than 1 microsecond during the test.

## 8.5 Solderability

- (1) Requirements: Solder-dipping section shall be covered by solder entirely.
- (2) Test method: Fluxed soldering section of shrouded header shall be dipped in solder of the following conditions.

#### INFRARED REFLOW CONDITION



RAMP UP  $2^{\circ}\text{C} \sim 3^{\circ}\text{C/Sec}$  Preheat

**RAMP** 150°℃~180°℃ UP

ramp down  $4^{\circ}\text{C} \sim 7^{\circ}\text{C/Sec}$ 

90Sec  $\pm 30$ Sec 30sec.

T1:	temperature ramp up rate:	2°C ~3°C / sec
T2:	prehect: 150°C ~ 160°C	60~120sec
T3:	time Over 230°C:	5~15sec
	ramp down rate during cooling:	4°C ~7°C /sec
	peak temperature :	240°C Max

(3) Test result : Good.



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8.6 Resistance to soldering heat

(1) Requirements: There shall be no deformation nor damage which may affect the performance.

(2) Test method: Specimen shall be mounted on a PCB (inserted only) and subjected to resistance to soldering heat test of the following conditions.

Solder temperature : 250±5 °C Immersion period : 3-5 seconds

(3) Test result: Good.